### SN74LS19A, SN74LS24A SCHMITT-TRIGGER POSITIVE-NAND GATES AND INVERTERS WITH TOTEM-POLE OUTPUTS

JANUARY 1981 - REVISED MARCH 1988

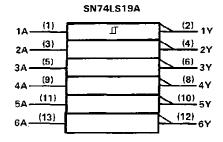
- Functionally and Mechanically Identical to 'LS13, 'LS14, and 'LS132, Respectively
- Improved Line-Receiving Characteristics
- P-N-P Inputs Reduce System Loading
- Excellent Noise Immunity with Typical Hysteresis of 0.8 V

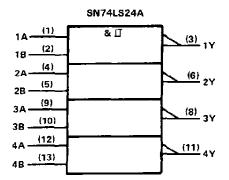
#### description

Each circuit functions as a NAND gate or inverter, but because of the Schmitt action, it has different input threshold levels for positivegoing  $\{V_{T+}\}$  and for negative-going  $\{V_{T-}\}$  signals. The hysteresis or backlash, which is the difference between the two threshold levels  $\{V_{T+} - V_{T-}\}$ , is typically 800 millivolts.

These circuits are temperature-compensated and can be triggered from the slowest of input ramps and still give clean, jitter-free output signals.

#### logic symbols†





<sup>&</sup>lt;sup>†</sup> These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# SN74LS19A . . . D. J, OR N PACKAGE (TOP VIEW)

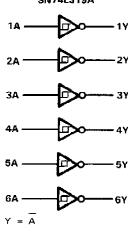
	_		_
1A 🗌	1	<b>U</b> 14	□vcc
1Y 🗌	2	13	□6A
2A 🗌	3	12	<u>∏</u> 6Y
2Y 🗀	4	11	]5A
3A 🗌	5	10	_5Y
3Y 🖺	6	9	<b>□4A</b>
GND 🗌	7	8	<b>□4</b> Y

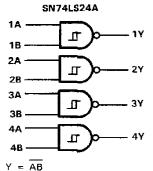
# SN74LS24A . . . D, J, OR N PACKAGE (TOP VIEW)

1A   1	14	V C (
1B   2	13	4B
1Y   3	12	4A
2A   4	11	4Y
2B   5	10	3B
	11 10 9 8	ļ,

#### logic diagrams (positive logic)

#### SN74LS19A

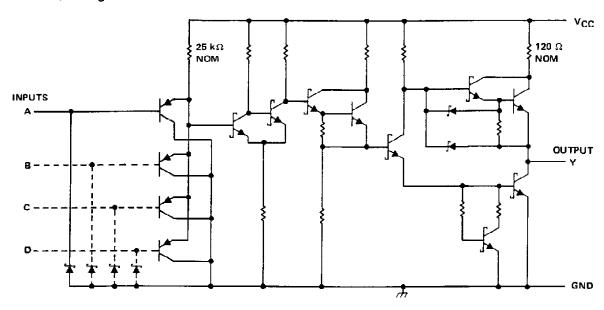




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## schematic (each gate)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage	7 V
Operating free-air temperature range 0°C to 7	70°C
Storage temperature range65°C to 15	50°C

#### recommended operating conditions

	MIN	мом	MAX	UNIT
Supply voltage, VCC	4.75	5	5.25	V
High-level output current, IOH			-400	μΑ
Low-level output current, IQL			8	mA
Operating free-air temperature, TA	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDIT	MIN	TYP‡	MAX	UNIT	
V <sub>T +</sub>	V <sub>CC</sub> = 5 V			1.65	1.9	2.15	V
٧٢_	V <sub>CC</sub> = 5 V			0.75	1.0	1.25	V
Hysteresis (VT+ - VT-)	V <sub>CC</sub> = 5 V			0.4	0.9		V
VIK	VCC = MIN.	ij = -18 mA			-1.5		V
VoH	V <sub>CC</sub> → MIN,	V <sub>I</sub> ÷ V <sub>T-min</sub>	I <sub>OH</sub> = -0.4 mA	2.7	3.4		V
V	V BAINI	V. – V–	$I_{OL} = 4 \text{ mA}$		0.25	0.4	v
VOL	V <sub>CC</sub> = MIN,	V  = VT + max	I <sub>OL</sub> = 8 mA		0.35	0.5	ľ
<sup>1</sup> Τ+	Vcc = 5 V.	V <sub>I</sub> = V <sub>T+</sub>			-2	- 20	$\mu \Delta$
I <sub>T</sub> _	$V_{CC} = 5 V$ ,	V <sub>I</sub> = V <sub>T</sub> =			-5	- 30	μΑ
11	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 7 V			0.1		mΑ
lн	$V_{CC} = MAX$	V <sub>I</sub> = 2.7 V	-			20	μА
1 <sub>է</sub> ը	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0.4 V				- 50	μА
los⁵	V <sub>CC</sub> = MAX,	$V_1 = V_0 = 0 V$		- 20		- 100	mΑ
	\/ MAY	V- 0.V	'LS19A		9.9	18	4
ıссн	V <sub>CC</sub> = MAX,	ν <sub>1</sub> = υ ν	'LS24A		6.6	12	mA
	M BEAV	)/ 4.F.\/	'LS19A		17	30	
<sup>1</sup> CCL	VCC = MAX.	V  = 4.5 V	'LS24A		11	20	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, VCC - 5 V, TA - 25 °C (see Figure 1)

0404145750	FROM	то	TEST CONDITIONS	Sf	174LS1	9A	SN	174L\$24		UNIT
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	ONII
tPLH .	Any	Y	R <sub>I</sub> = 2 kΩ. C <sub>I</sub> = 15 pF		13	20		13	20	ns
tPHL	Any	Υ	$R_L = 2 k\Omega$ , $C_L = 15 pF$		18	30		25	40	ns

tplH = Propagation delay time, low-to-high-level output

tpHL = Propagation delay time, high-to-low-level output

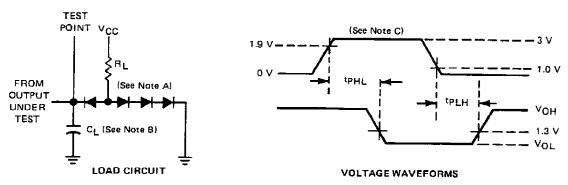


 $<sup>^4</sup>$  All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25 °C.

Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

## SN74LS19A, SN74LS24A SCHMITT-TRIGGER POSITIVE-NAND GATES AND INVERTERS WITH TOTEM-POLE OUTPUTS

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. All diodes are IN3064 or equivalent.

- B.  $C_L$  includes probe and circuit capacitance.
- C. The generator characteristics are: PRR = 1 MHz,  $t_r$  = 15 ns,  $t_p$  = 6 ns,  $Z_0$  = 50  $\Omega$ .

FIGURE 1

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74LS19ADR	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS19A
SN74LS19ADR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS19A
SN74LS19AN	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS19AN
SN74LS19AN.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS19AN
SN74LS19ANSR	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS19A
SN74LS19ANSR.A	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS19A
SN74LS19ANSR.B	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS19A

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



# **PACKAGE OPTION ADDENDUM**

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# **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS19ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS19ANSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS19ADR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LS19ANSR	SOP	NS	14	2000	353.0	353.0	32.0

# **PACKAGE MATERIALS INFORMATION**

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#### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LS19AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS19AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS19AN.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS19AN.A	N	PDIP	14	25	506	13.97	11230	4.32



SMALL OUTLINE INTEGRATED CIRCUIT



#### NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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